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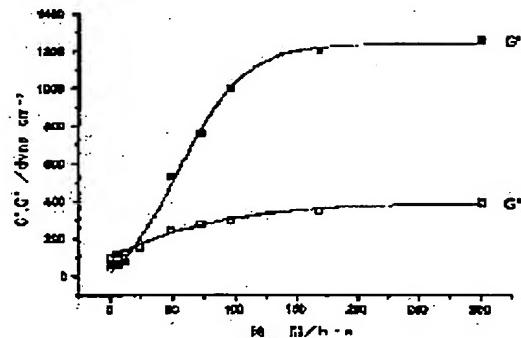
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## (54) PHOTORESISTIVE RESIN COMPOSITION

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain a photosensitive resin compsn. using a relatively small amt. of Fullerene and curable with visible light.

**SOLUTION:** This photosensitive resin compsn. contains Fullerene and a high molecular compd. having a functional group capable of reacting with the Fullerene under irradiation with visible light. A negative type image element is formed as follows; a layer of this compsn. is formed and irradiated with visible light through a photomask having a visible radiation transmitting pattern, the irradiated part in the layer is cured and the uncured part in the layer is removed to form a patterned resist film. A device is produced by etching an image forming layer through the resist film and then removing the resist film.



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